



Material Content Data Sheet



Sales Product Name		BGS 18GA14 E6327		Issued		3. July 2019		
MA#		MA004221206						
Package		PG-ATSLP-14-9		Weight*		6.65 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.264	3.98	3.98	39762	39762
bumps	non noble metal	copper	7440-50-8	0.020	0.31	0.31	3072	3072
encapsulation	organic material	carbon black	1333-86-4	0.025	0.38		3764	
	plastics	epoxy resin	-	0.726	10.91		109145	
	inorganic material	silicondioxide	60676-86-0	4.255	63.98	75.27	639812	752721
leadfinish	noble metal	gold	7440-57-5	0.078	1.18		11753	
	non noble metal	nickel	7440-02-0	0.089	1.34	2.52	13404	25157
substrate	organic material	carbon black	1333-86-4	0.002	0.02		249	
	plastics	epoxy resin	-	0.065	0.97		9723	
	inorganic material	silicondioxide	60676-86-0	0.486	7.31		73133	
	non noble metal	copper	7440-50-8	0.505	7.59	15.89	75882	158987
solder	noble metal	silver	7440-22-4	0.000	0.00		20	
	non noble metal	tin	7440-31-5	0.007	0.11	0.11	1094	1114
ubm	non noble metal	tungsten	7440-33-7	0.000	0.00		39	
	non noble metal	titanium	7440-32-6	0.000	0.01		74	
	non noble metal	copper	7440-50-8	0.001	0.02	0.03	209	322
solder resists	inorganic material	silicondioxide	60676-86-0	0.027	0.40		4009	
	inorganic material	bariumsulfate	7727-43-7	0.027	0.41		4056	
	plastics	acrylic resin	-	0.072	1.08	1.89	10800	18865
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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